



## Vishay Specialty Thin Film Introduces Thin Film Metallized Submount Platform

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**Malvern, PA — April 29, 2026—** Vishay Intertechnology, Inc. (NYSE: VSH) today announced its new [thin film submount platform](#), designed to support next-generation optical transceivers, RF modules, and advanced electronic packaging applications requiring high thermal performance, precision alignment, and high frequency signal integrity.

Known for delivering high performance thin film substrates that enable smaller, faster, and more efficient electronic systems in environments where conventional solutions fall short, Vishay uses precision deposition of passive circuit elements and precision machining of advanced ceramic substrates, including aluminum nitride (AlN). This approach delivers superior thermal conductivity, dimensional stability, and electrical performance in demanding environments through the new platform.

The platform is optimized for emerging applications in high speed data communications, including 800G, 1.6T, and 3.2T optical transceivers, where increasing power densities and tighter packaging constraints require enhanced heat dissipation, difficult alignment problems, and low loss interconnect performance. Vishay's thin film submounts enable designers to improve thermal management at the device level while maintaining precision alignment and signal integrity at high frequencies.

"Next-generation photonics and RF systems push the limits of thermal, mechanical, and electrical performance at the package level," said Michael Casper, vice president of specialty thin film at Vishay. "Our thin film submount platform provides engineers with a flexible solution that enables high performance without compromising reliability."

### **Key Features and Benefits:**

- Quick-turn prototyping with high volume production capability from three manufacturing locations
- [High thermal conductivity](#): AlN-based substrates support efficient heat dissipation for high power devices
- [High frequency performance](#): low loss thin film interconnects support microwave and millimeter-wave applications
- [Miniaturization](#): compact, integrated designs support space-constrained modules
- [Reduction in manufacturing complexity](#): pre-deposited AuSn or EPIG and precision machining support difficult manufacturing processes
- Design flexibility: tailored geometries, metallization schemes, and circuit integration support custom designs

Vishay's thin film submount platform is proven in a wide range of applications, including laser diode mounting, RF / microwave modules, optical alignment, combined wire bond and SMT processes, and hermetic packaging solutions. The company works closely with customers in defense, space, and high reliability industrial applications to develop designs that meet stringent performance and environmental requirements.

Vishay can provide samples and support custom designs now, supported by global production capabilities.

For more information, visit: <https://www.vishay.com/en/landingpage/sff/>